entrepix Our Expertise, Our Services, Your Success

Mirra Reflexion LK

The Applied Reflexion LK CMP provides production-proven, high performance planarization solutions for copper damascene, shallow trench isolation (STI), oxide, polysilicon, and tungsten applications. Its high-speed planarizing platens and multi-zone polishing heads enable superior uniformity and efficiency with low downforce for extendibility to < 45 nm device generations.

The integrated post-CMP Desica cleaner uses unique full-immersion Marangoni vapor drying technology to virtually eliminate watermark defects and dramatically reduce particle contamination. The Applied Reflexion LK CMP system also implements a full suite of endpoint methods, in-line metrology and advanced process control capabilities that ensure excellent within-wafer and wafer-to-wafer process control and repeatability for all planarization applications.

For AMAT refurbished equipment:
info@entrepix.com

For AMAT spare parts and upgrades:
parts@entrepix.com

For AMAT equipment service / maintenance:
service@entrepix.com

Or Call:
602-426-8677 (Sales)

Preventative Maintenance Program

Overview

- General Clean and Inspections
- Clean and Lubricate All Rails and Drives
- Baseline Equipment
- Load Calibrations
- Platen Run Out
- Arm Sweet Calibrations
- Carrier Run Out
- Down Force Calibration
- Back Pressure Calibrations
- Pad Conditioner Operations Check
- Unload Calibrations
- Tool-Specific Issues Addressed